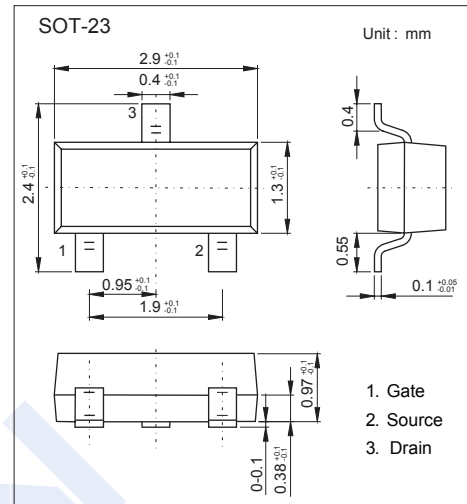
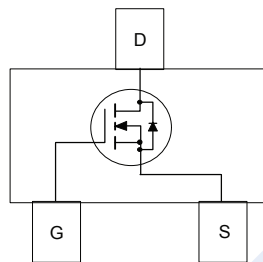


## N-Channel MOSFET

## WNM2016

## ■ Features

- $V_{DS}(V) = 20\text{ V}$
- $I_D = 3.2\text{ A}$
- $R_{DS(ON)} < 47\text{ m}\Omega$  @  $V_{GS} = 4.5\text{ V}$
- $R_{DS(ON)} < 55\text{ m}\Omega$  @  $V_{GS} = 2.5\text{ V}$
- $R_{DS(ON)} < 66\text{ m}\Omega$  @  $V_{GS} = 1.8\text{ V}$

■ Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	10 S	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	20		V	
Gate-Source Voltage	$V_{GS}$	$\pm 8$			
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>a</sup>	$I_D$	$T_A = 25^\circ\text{C}$	3.2	2.9	A
		$T_A = 70^\circ\text{C}$	2.5	2.3	
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25^\circ\text{C}$	0.8	0.7	W
		$T_A = 70^\circ\text{C}$	0.5	0.4	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>b</sup>	$I_D$	$T_A = 25^\circ\text{C}$	2.9	2.7	A
		$T_A = 70^\circ\text{C}$	2.3	2.1	
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_A = 25^\circ\text{C}$	0.6	0.5	W
		$T_A = 70^\circ\text{C}$	0.4	0.3	
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	10		A	
Thermal Resistance.Junction- to-Ambient <sup>a</sup>	$R_{thJA}$	150	175	$^\circ\text{C}/\text{W}$	
Thermal Resistance.Junction- to-Ambient <sup>b</sup>	$R_{thJA}$	180	210		
Junction-to-Case Thermal Resistance	$R_{thJC}$		76		
Junction Temperature	$T_J$	150		$^\circ\text{C}$	
Storage Temperature Range	$T_{stg}$	-55 to 150			

Notes:

a Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.

b Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.

c Repetitive rating, pulse width limited by junction temperature,  $t_p = 10\mu\text{s}$ , Duty Cycle=1%d Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$ .

## N-Channel MOSFET

## WNM2016

■ Electrical Characteristics  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{DS}$	$I_D=250\ \mu\text{A}$ , $V_{GS}=0\text{V}$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=16\text{V}$ , $V_{GS}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 8\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_D=250\ \mu\text{A}$	0.4		1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{V}$ , $I_D=3.6\ \text{A}$			47	m $\Omega$
		$V_{GS}=2.5\text{V}$ , $I_D=3.1\ \text{A}$			55	
		$V_{GS}=1.8\text{V}$ , $I_D=1\ \text{A}$			66	
Forward Transconductance	$g_{FS}$	$V_{DS}=5\ \text{V}$ , $I_D=3.1\ \text{A}$		8.5		S
Input Capacitance	$C_{iss}$	$V_{GS}=0\text{V}$ , $V_{DS}=10\ \text{V}$ , $f=1\text{MHz}$		500		pF
Output Capacitance	$C_{oss}$			62		
Reverse Transfer Capacitance	$C_{rss}$			58		
Total Gate Charge	$Q_{g(tot)}$	$V_{GS}=4.5\ \text{V}$ , $V_{DS}=10\ \text{V}$ , $I_D=3.1\ \text{A}$		8.5		nC
Threshold Gate Charge	$Q_{g(th)}$			0.45		
Gate Source Charge	$Q_{gs}$			0.65		
Gate Drain Charge	$Q_{gd}$			3.1		
Turn-On DelayTime	$t_{d(on)}$	$V_{GS}=4.5\ \text{V}$ , $V_{DS}=10\ \text{V}$ , $R_L=3.5\ \Omega$ , $R_G=6\ \Omega$		12		ns
Turn-On Rise Time	$t_r$			20.8		
Turn-Off DelayTime	$t_{d(off)}$			38.8		
Turn-Off Fall Time	$t_f$			10.8		
Diode Forward Voltage	$V_{SD}$	$I_S=1\ \text{A}$ , $V_{GS}=0\text{V}$			1.5	V

## ■ Marking

Marking	WT6*
---------	------

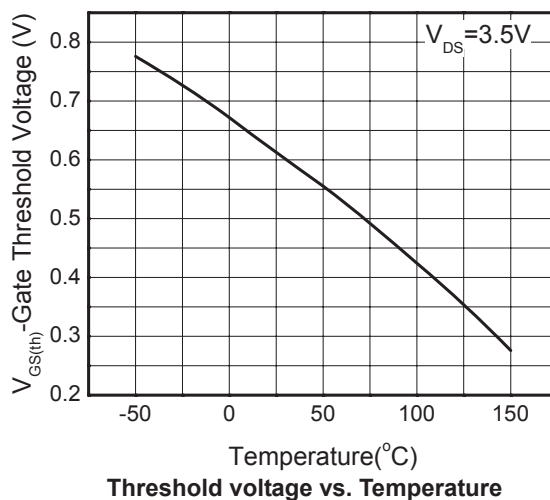
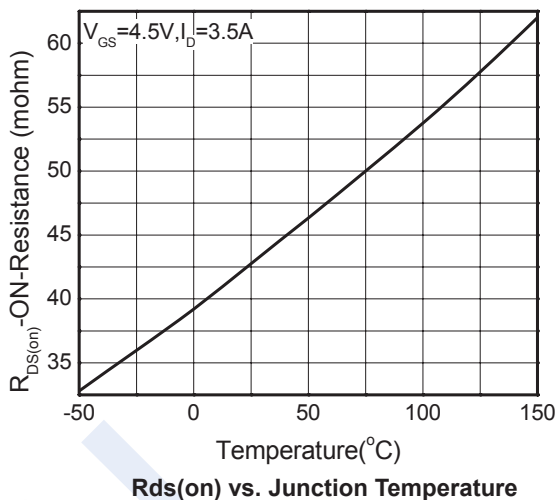
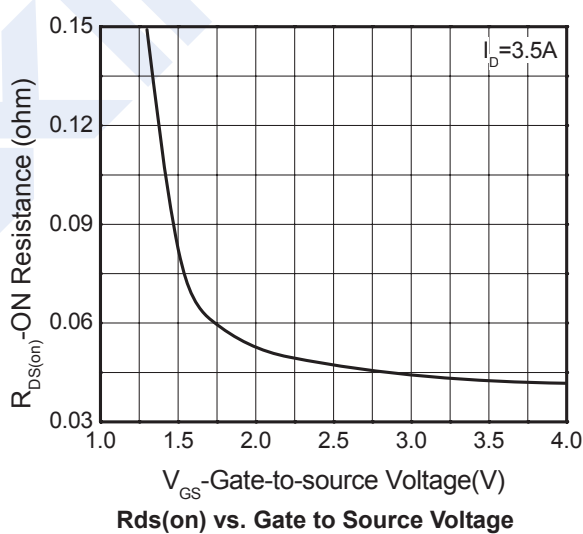
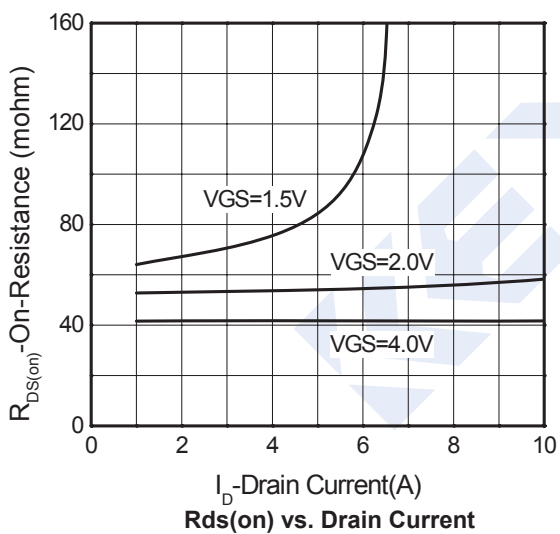
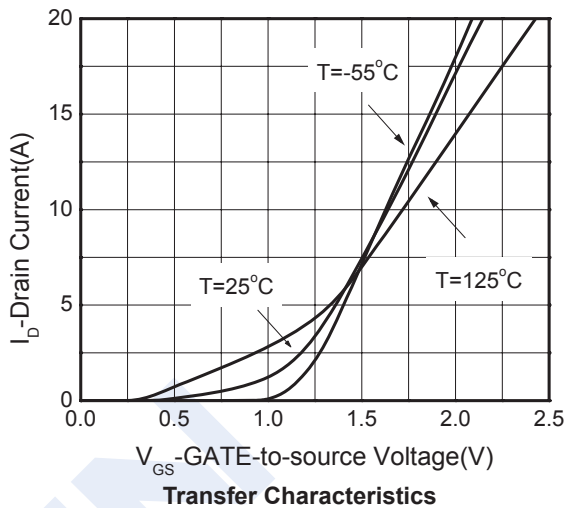
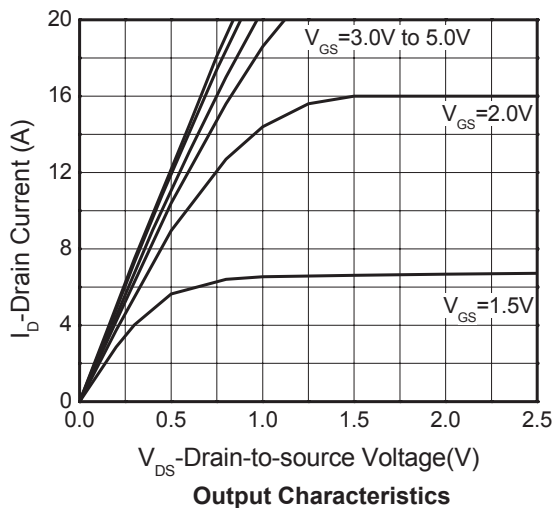
WT6 = Device Code

\* = Month (A~Z)

# N-Channel MOSFET

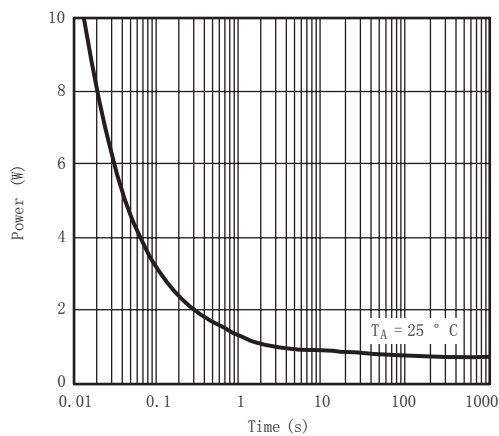
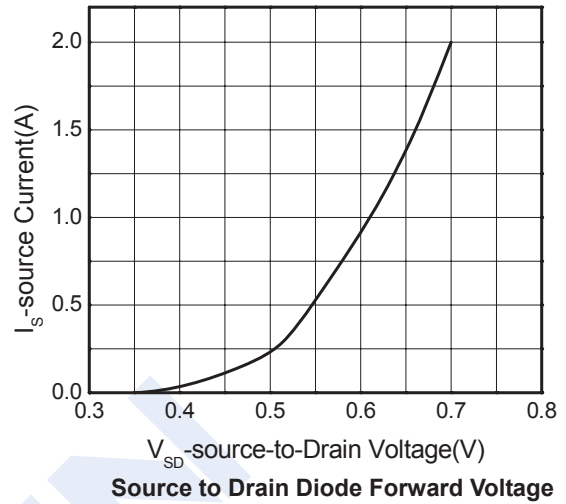
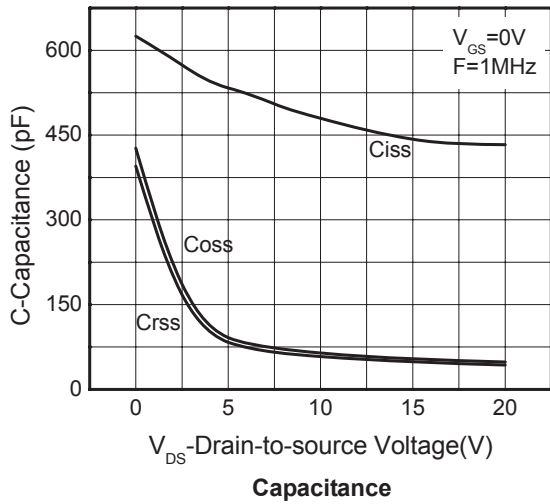
## WNM2016

■ Typical Characteristics

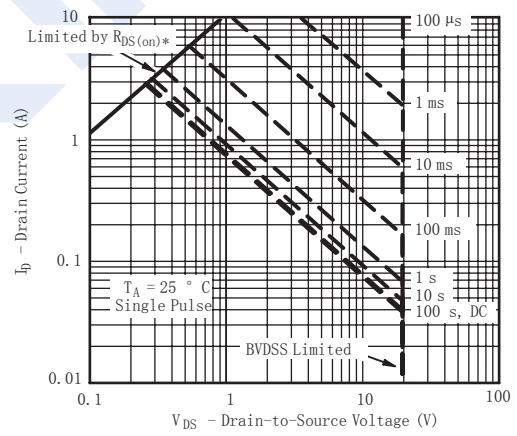


# N-Channel MOSFET

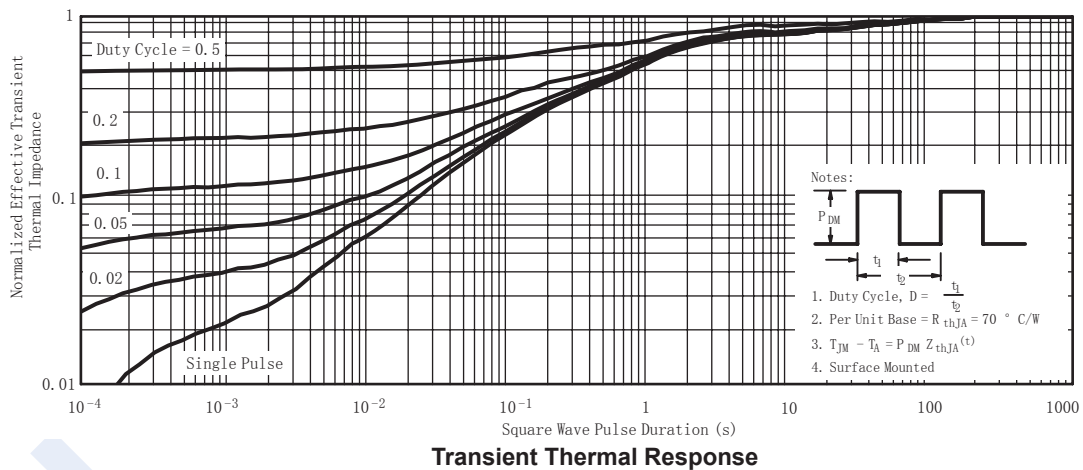
## WNM2016



Single Pulse Power



Safe Operating Area



Transient Thermal Response